TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSIII)

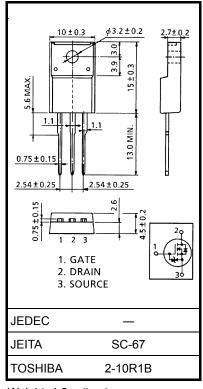
2SK2718

DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance $: RDS (ON) = 5.6 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 2.0 \text{ S}$ (typ.)
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 720 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	900	V
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	900	V
Gate-source voltage	_	V _{GSS}	±30	V
Drain current	DC (Note 1)	۱ _D	2.5	А
	Pulse (Note 1)	I _{DP}	7.5	А
Drain power dissipation	n (Tc = 25°C)	PD	40	W
Single pulse avalanche energy (Note 2)		E _{AS}	216	mJ
Avalanche current		I _{AR}	2.5	А
Repetitive avalanche e	energy (Note 3)	E _{AR}	4.0	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	3.125	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 63.4 mH, R_G = 25 Ω , I_{AR} = 2.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution. Unit: mm

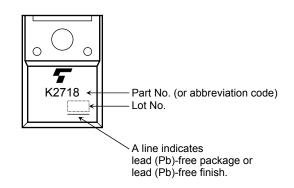
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V		_	±10	μA
Gate-source br	eakdown voltage	V _(BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V		_	100	μA
Drain-source br	reakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1.5 A		5.6	6.4	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 20 V, I _D = 1.5 A	1.0	2.0	_	S
Input capacitance	ce	C _{iss}			510	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	10	_	
Output capacitance		C _{oss}			55	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{_{0V}} \prod_{UC} \stackrel{ID=1.5A}{_{Vout}} \circ V_{out}$ $R_{L} = 267\Omega$ $V_{DD} = 400V$	_	20	_	
	Turn-on time	t _{on}		_	60	_	
	Fall time	t _f		_	40	_	- ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs	_	115	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	21	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 2.5 A		11	_	nC
Gate-drain ("miller") Charge		Q _{gd}			10	—	

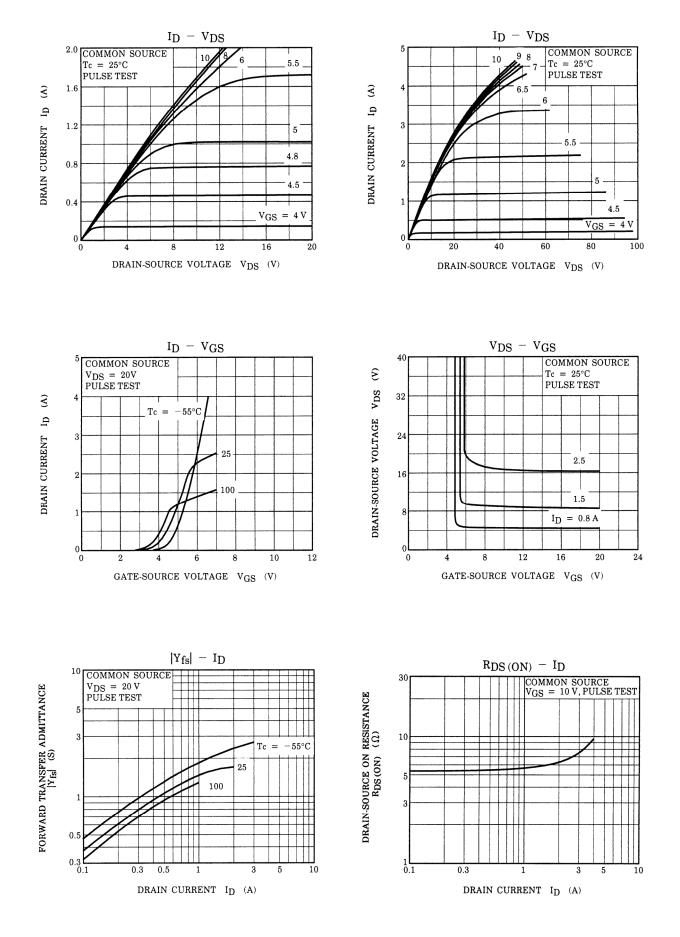
Source–Drain Ratings and Characteristics (Ta = 25°C)

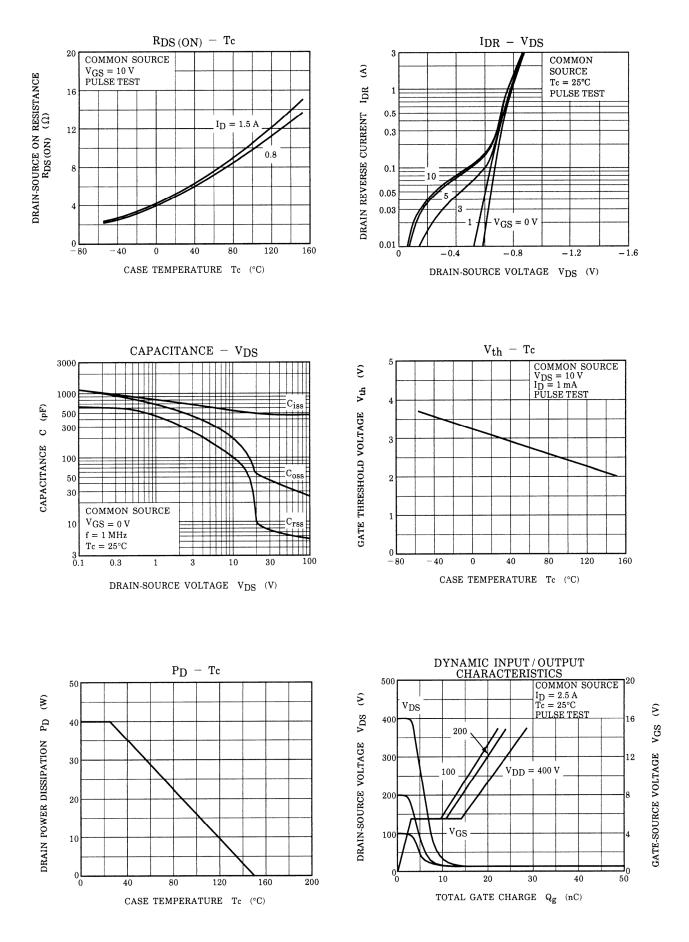
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	2.5	А
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	7.5	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 2.5 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 2.5 A, V _{GS} = 0 V	-	960	_	ns
Reverse recovery charge	Qrr	dI _{DR} / dt = 100 Å / µs	-	5.3	_	μC

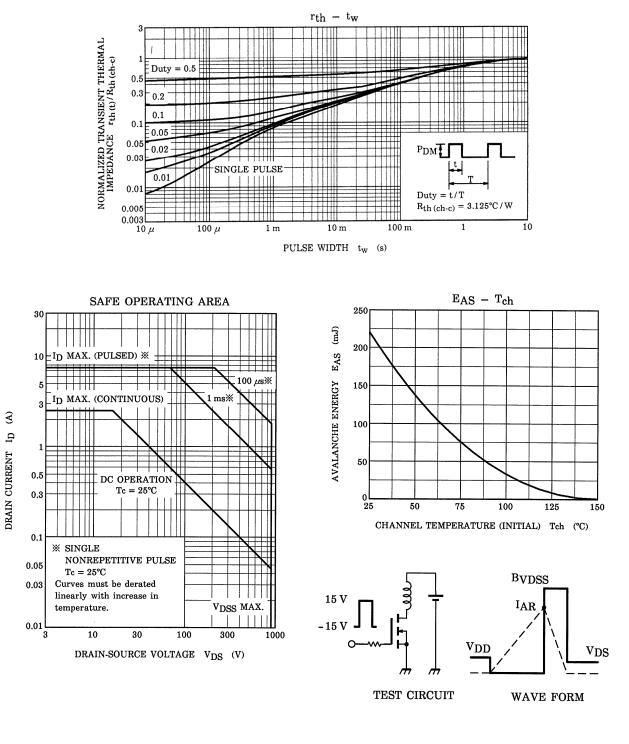
Marking



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 $\begin{array}{ll} \mathrm{R}_{\mathrm{G}} = 25 \ \Omega \\ \mathrm{V}_{\mathrm{DD}} = 90 \ \mathrm{V}, \ \mathrm{L} = 63.4 \ \mathrm{mH} \end{array} \qquad \mathrm{EAS} = \frac{1}{2} \cdot \mathrm{L} \cdot \mathrm{I}^2 \cdot \left(\frac{\mathrm{B} \mathrm{VDSS}}{\mathrm{B} \mathrm{VDSS} - \mathrm{V}\mathrm{DD}} \right) \end{array}$

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